High Density Interconnect PCB Market Research Report – Global Forecast till 2023

Market Synopsis

Globally, the High-Density Interconnect (HDI) Printed Circuit Board (PCB) Market is expected to grow from USD 8,683.9 million in 2018 to USD 15,600.6 million by 2023, at a CAGR of 12.4% during the forecast period, 2018–2013.

HDI PCB have a higher circuitry density than a traditional PCB, which means it allows designers to place more components on an HDI PCB. Shorter distance between the electronic components and smaller size of the components help in reduced signal loss and crossing delays, resulting into faster transmission of signals from one part to another.

The increasing need for smaller, energy-efficient, and high-performance PCBs acts as the major driving factor for the growth of HDI PCB market globally. This has helped the overall electronics industry to produce smarter, lighter, faster, and smaller products. For instance, in the last two decades, the cellular mobile phone market has experienced tremendous innovation, from simple monochromatic display and basic voice call capability to feature rich computing device with high-resolution touch screen, camera, fast internet connectivity, GPS, music player, and many more. Similarly, heavy desktop computers during 1990s are now advanced to faster and smaller laptops with the help of HDI PCBs. Despite major developments, the high cost associated with manufacturing and lack of expertise in manufacturing are hampering the market growth.

Although, HDI PCB are used in multiple industries but some of its prominent industry verticals include consumer electronics, telecom and IT, manufacturing, automotive, and medical devices. The consumer electronics industry vertical is the largest contributor in the HDI PCB Market due to the wide adoption of HDI PCBs in the computing and smartphone market segments whereas automotive market segment is expected to grow with the highest CAGR during the forecast period due to increasing digitalization of cars and its advancement towards autonomous and connected cars.

Global HDI PCB Market

Source: MRFR Analysis
Segmentation.
The global HDI PCB Market is segmented into number of high-density interconnection layer, industry vertical, and regions/country.

By number of high density interconnection layer, the market is segmented into 1, 2, and all.
By industry vertical, the market is segmented into consumer electronics, military and defense, telecom and IT, automotive, manufacturing, medical devices, and others.

By region, the market is segmented into North America, Europe, Asia-Pacific, and rest of the world.

Regional Analysis
The global market for HDI PCB is estimated to grow at a significant rate during the forecast period from 2018 to 2023. The geographical analysis of global HDI PCB Market is studied for North America, Europe, Asia-Pacific, and rest of the world.

North America is expected to dominate the HDI PCB market during the forecast period. North America region is considered as most advanced region in terms of development and adoption of innovative technologies in the field of semiconductors. The region has a huge potential for revenue generation in the HDI PCB market, particularly from automotive and consumer electronics industry verticals. US is expected to be the dominating country in the HDI PCB market in North America region during the forecast period.

Asia-Pacific is expected to grow at the fastest rate during the forecast period. Availability of low cost technologies and presence of many electronic devices manufacturing firms in the region are some of the driving factors for the HDI PCB market in the region. China, Japan, and India have been the leading countries in the Asia-Pacific region in terms of market share and this trend is expected to continue in the upcoming years.

Competitive Analysis
The HDI PCB market offers tremendous new opportunity as well as intense competition. The nature of the electronics industry creates a competitive landscape that is continuously evolving, emerging, and expanding. To meet the dynamic requirements of the customers, the major vendors are majorly focusing on new product development through increased investments in research & development (R&D) activities or through acquisitions. According to the latest trends in the HDI PCB market, more number of acquisitions are expected in the market.

Key players
The prominent players in HDI PCB Market are Epec, LLC (US), TTM Technologies (US), PCBCART (China), Millennium Circuits Limited (US), RAYMING (China), Mistral Solutions Pvt. Ltd. (India), SIEERRA CIRCUITS, INC. (US), Advanced Circuits (US), FUJITSU INTERCONNECT TECHNOLOGIES LIMITED (Japan), FINELINE Ltd. (Israel), and Austria Technologie & Systemtechnik Aktiengesellschaft (Austria).

Intended Audience
- HDI PCB manufacturers
- Electronic product manufacturers
- Resellers and Distributors
- Standard Making Bodies and Associations
- Automotive and Manufacturing Industries
- Custom electronic product developers

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